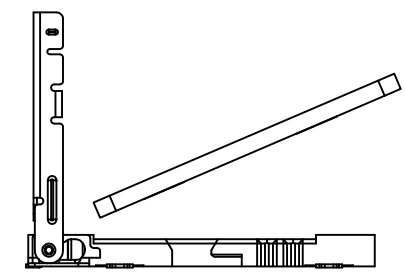
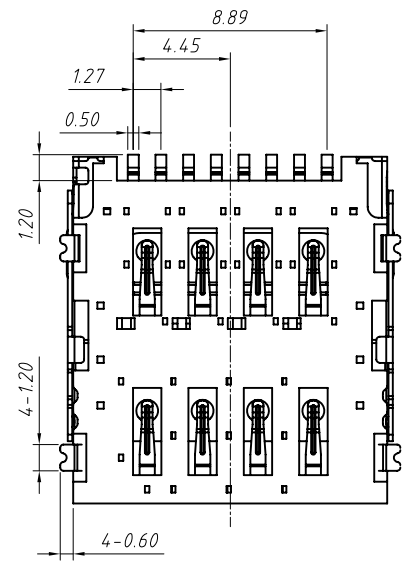
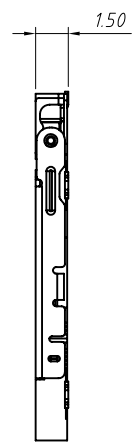
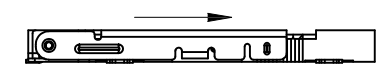


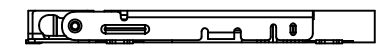
SECTION:A-A



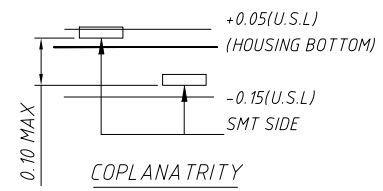
STEP 1 INSERT Micro-SIM CARD



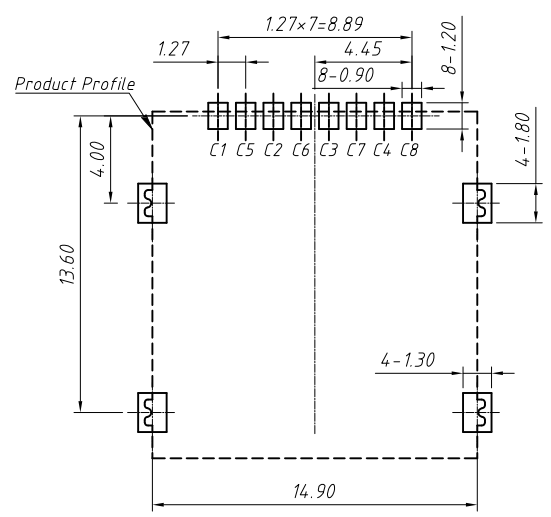
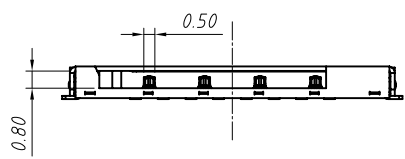
STEP 2 PUSH THE SHELL



STEP 3 FINISH



COPLANARITY




RECOMMENDED PCB LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

SIM Card	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I / O
C8	Reserved

Material
 Housing: Thermoplastic, UL 94 V-0.
 Terminal: Phosphor Bronze, T=0.15, Ni Plated Under, Au Plated On Contact Area, G/F Plated On Solder tail.
 Shell: Stainless Steel, T=0.15, Ni Plated Under, G/F Plated On Solder tail.

Electrical
 Contact Resistance: 60mΩ Max.
 Insulation Resistance: 1000MΩ Min.
 Dielectric Withstanding Voltage: 500V AC For 1 Minute.
 Operation Temperature Range: -25°C TO +70°C.
 Durability: 5000 Cycles.

GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION		Description:	
X	±0.15	X	±5°	UNITS	mm	Micro SIM CONN; HINGED TYPE; 8Pin H1.5mm L-KLS1-SIM-089-8P-H1.5-R	
.X	±0.03	.X	±3°	SHEET SIZE	A4		
.XX	±0.05	.XX	±2°	KLS P/N:			
Draw by:	Jenny	Date:	2018-03-10	 NingBo KLS ELECTRONIC CO.,L TD.			
Check by:		Date:	2018-03-10				
SCALE		SHEET	1	OF	1		